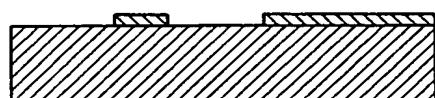
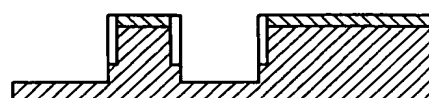




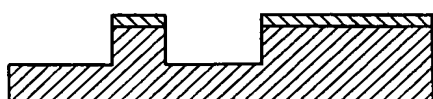
FIG. 1  
(Prior Art)



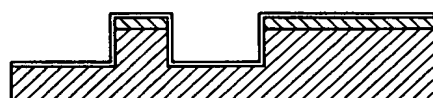
Oxide deposition  
and patterning



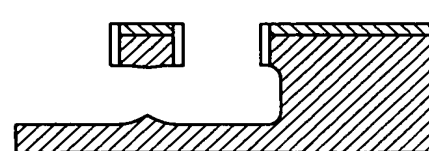
Silicon deep etch



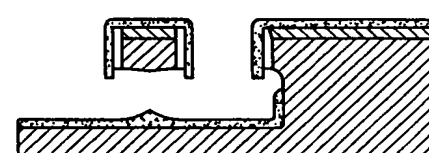
Silicon deep etching



Sidewall passivation



Release etch



Sputter metallization



not  
approved  
jc 6/13/03



FIG. 2  
(Prior Art)

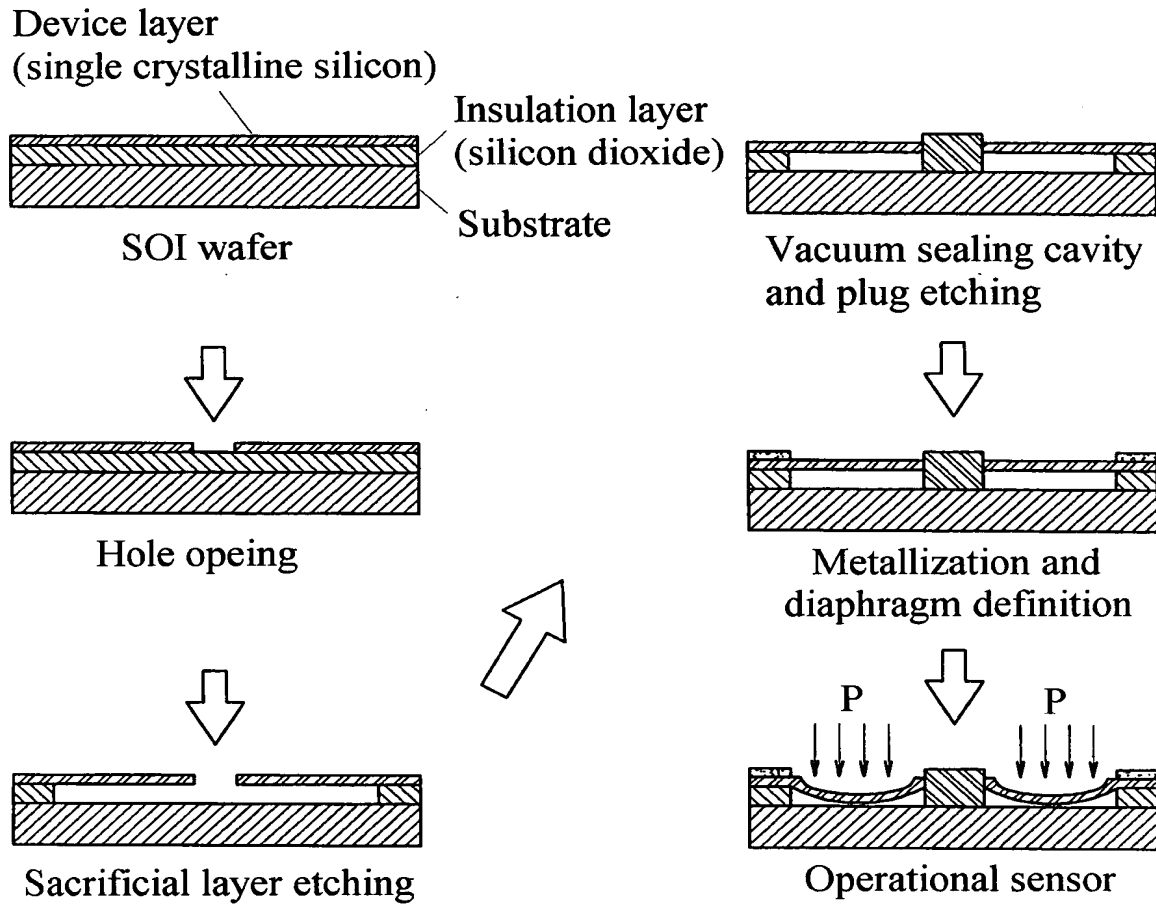




FIG. 3  
(Prior Art)

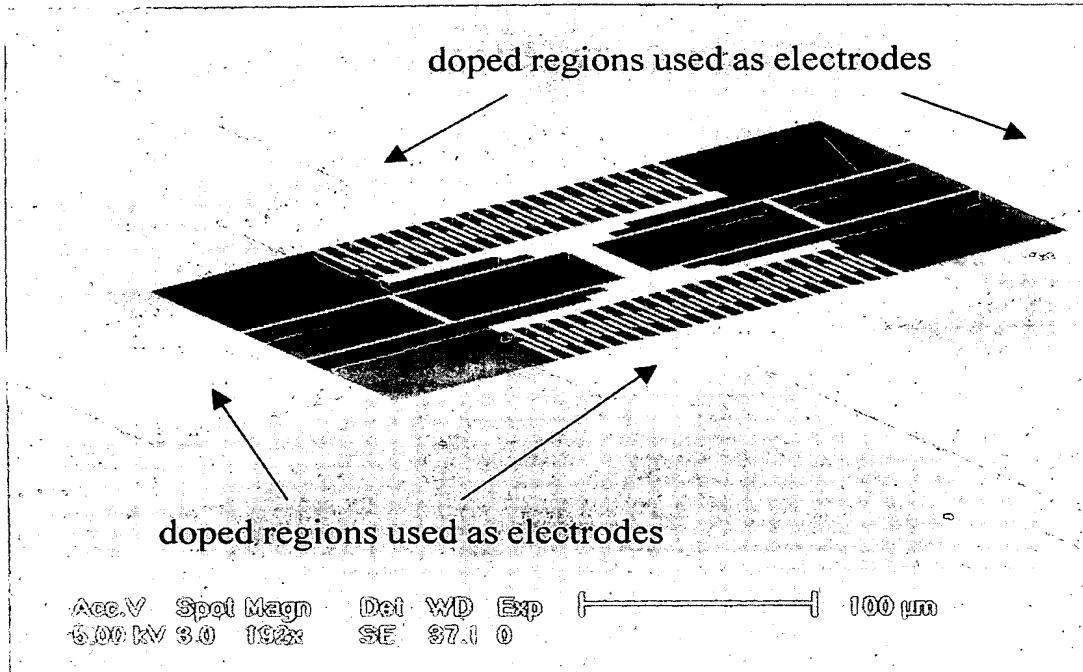




FIG. 4  
(Prior Art)

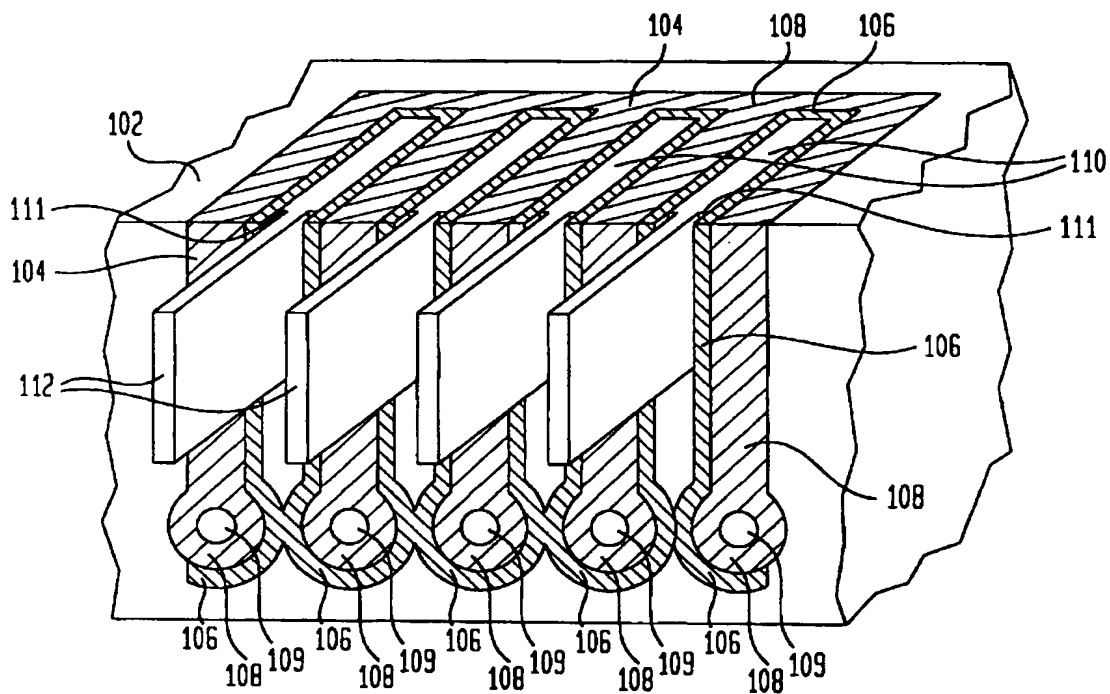
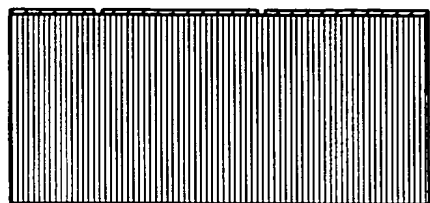
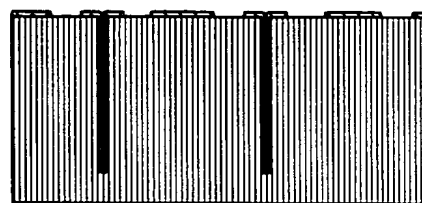




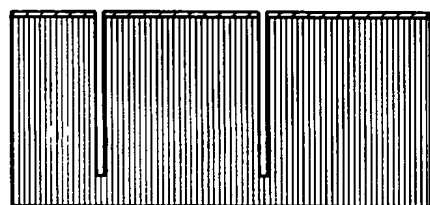
FIG. 5  
(Prior Art)



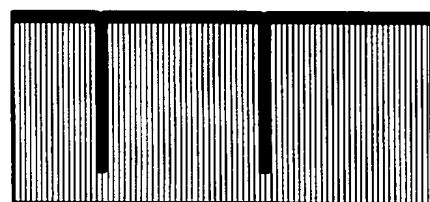
First etch mask deposition and patterning



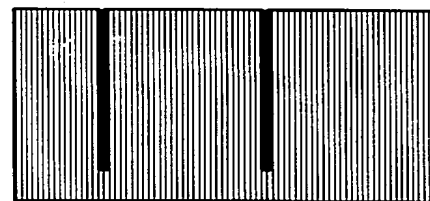
Second etch mask deposition and patterning



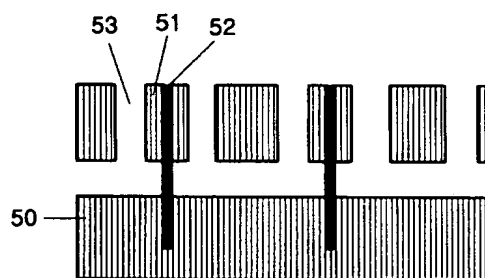
Deep silicon etching to form trenches



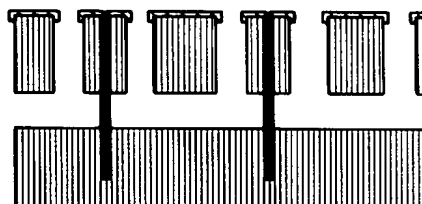
Trench filling by oxidation



Top oxide removal



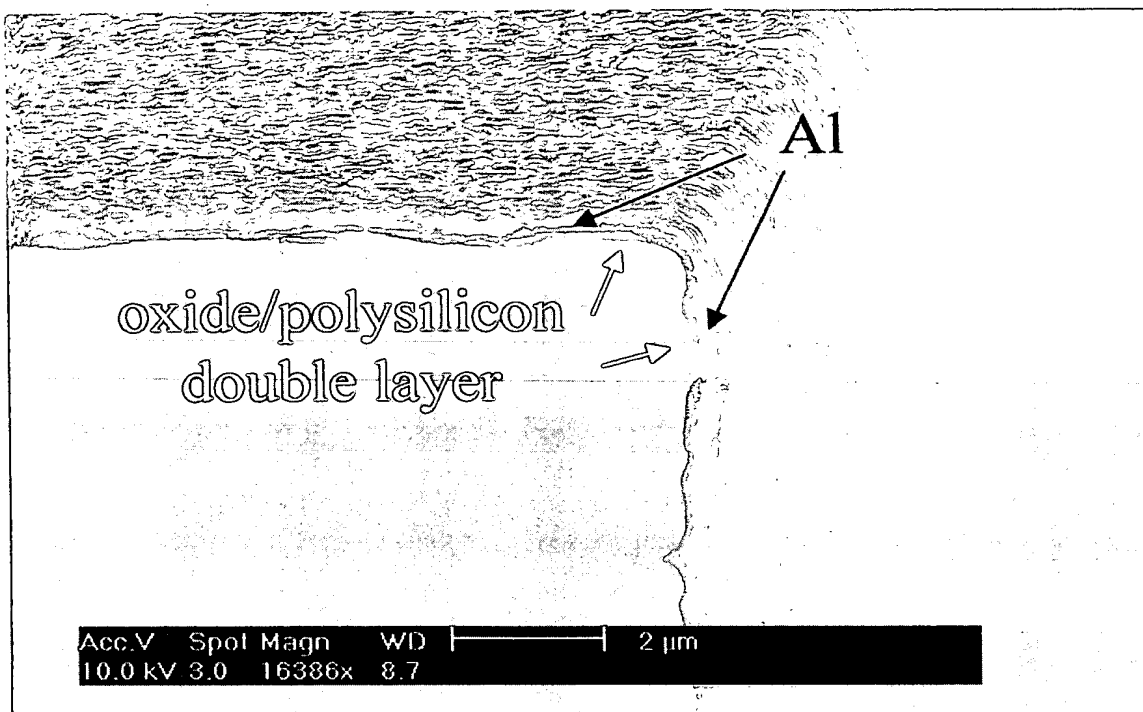
Structure fabrication



Metallization



FIG. 7A



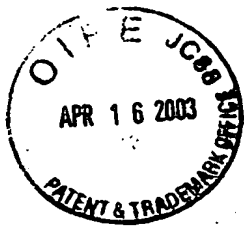


FIG. 7B

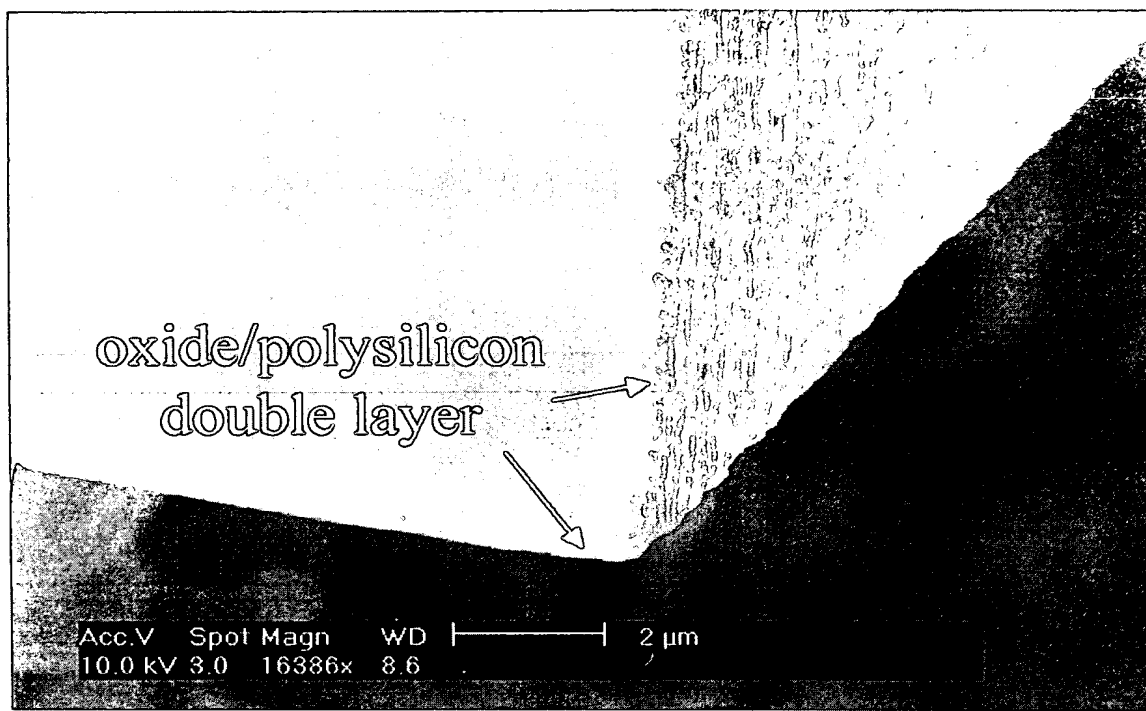




FIG. 9

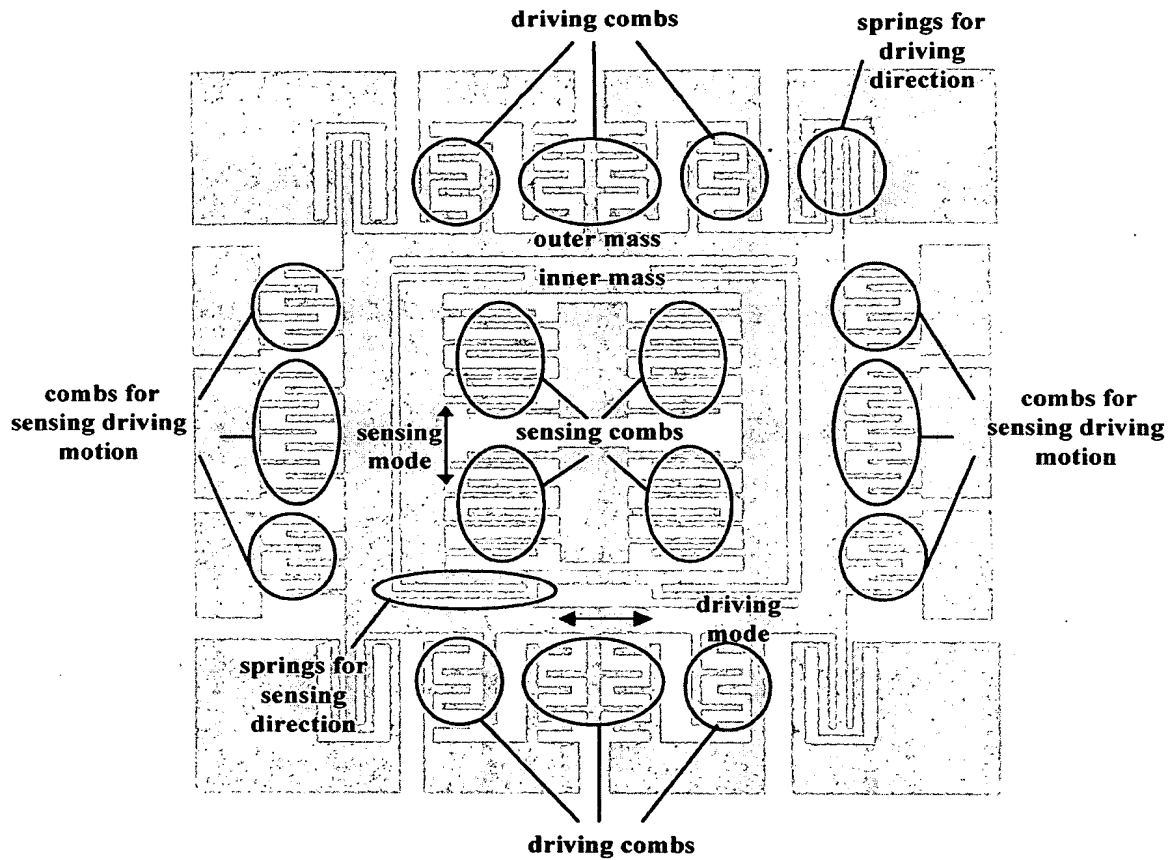






FIG. 12A

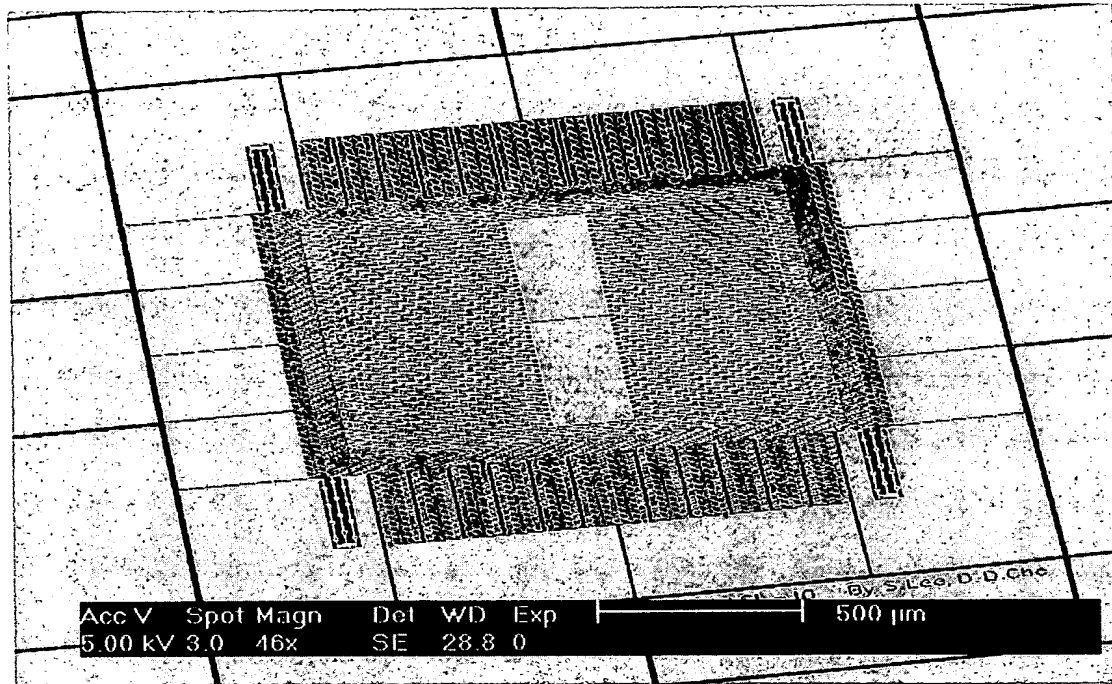
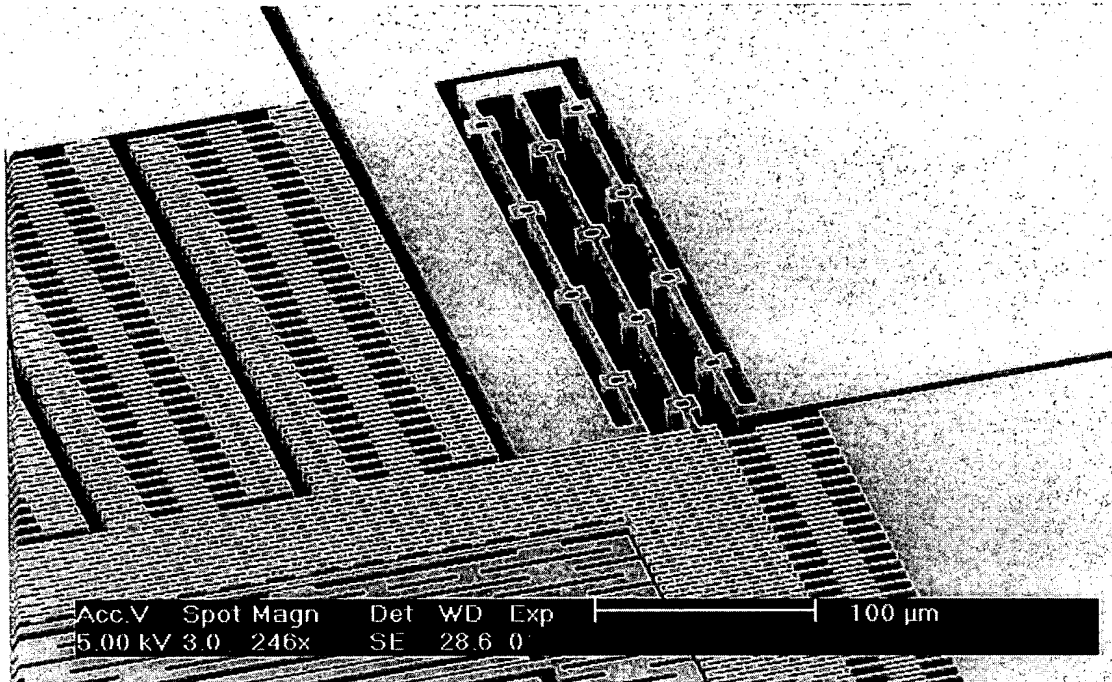




FIG. 12B



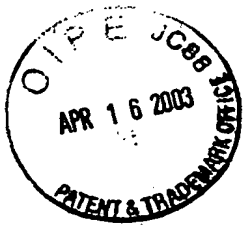


FIG. 12C

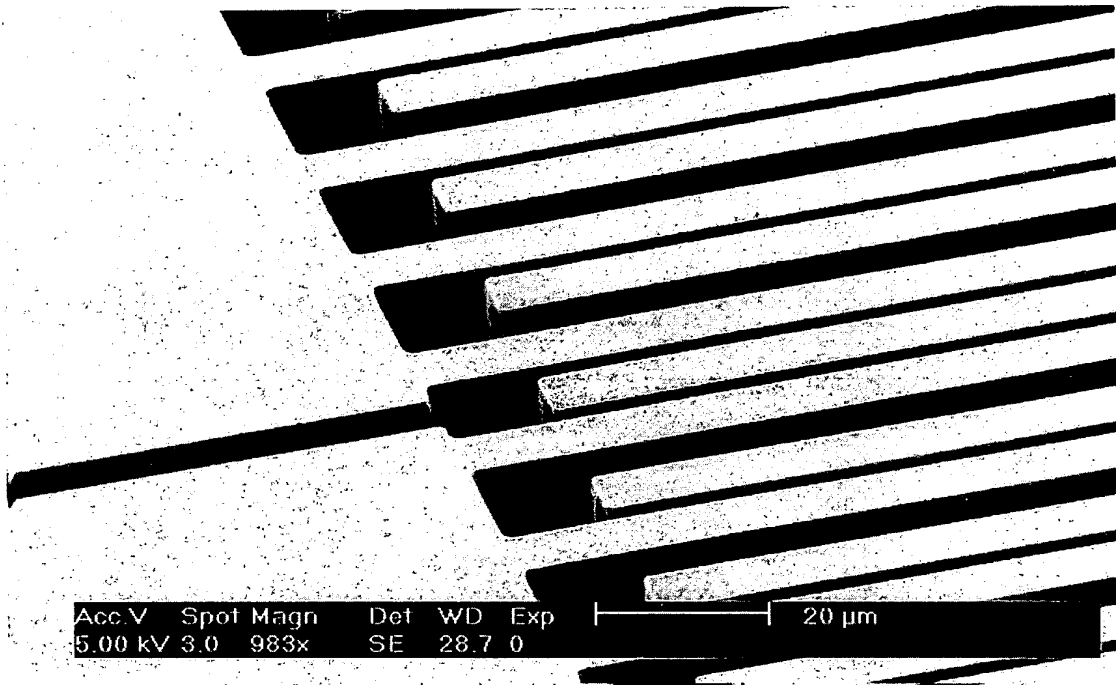
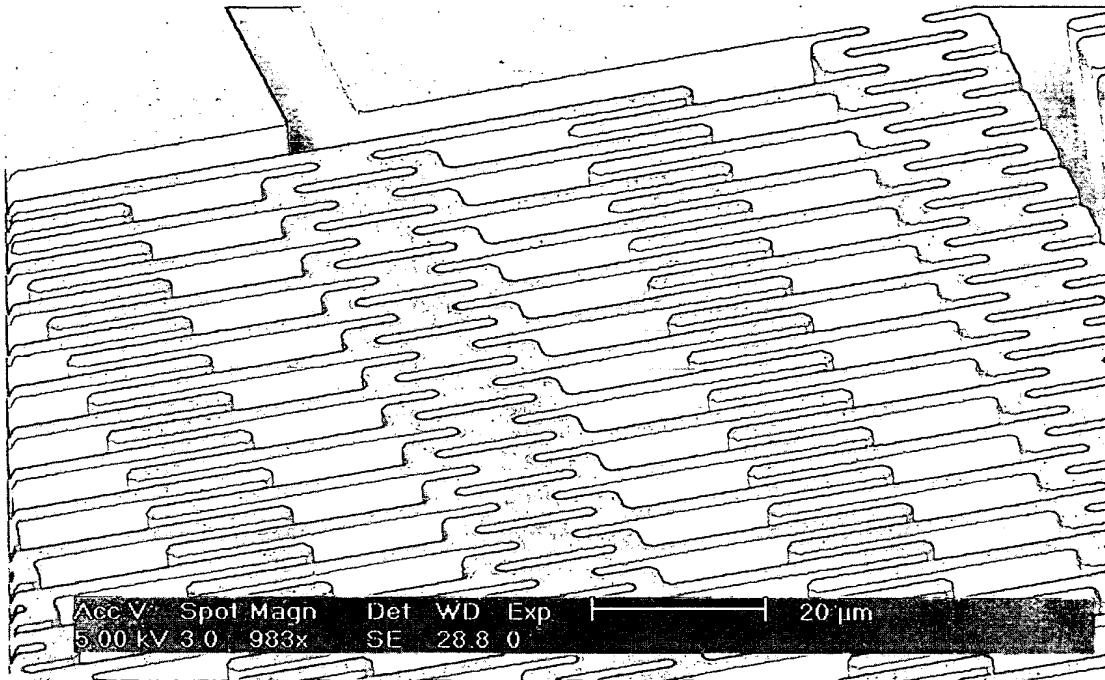




FIG. 12D



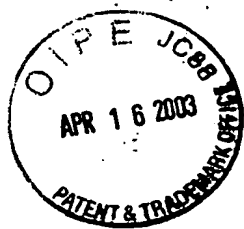


FIG. 12E

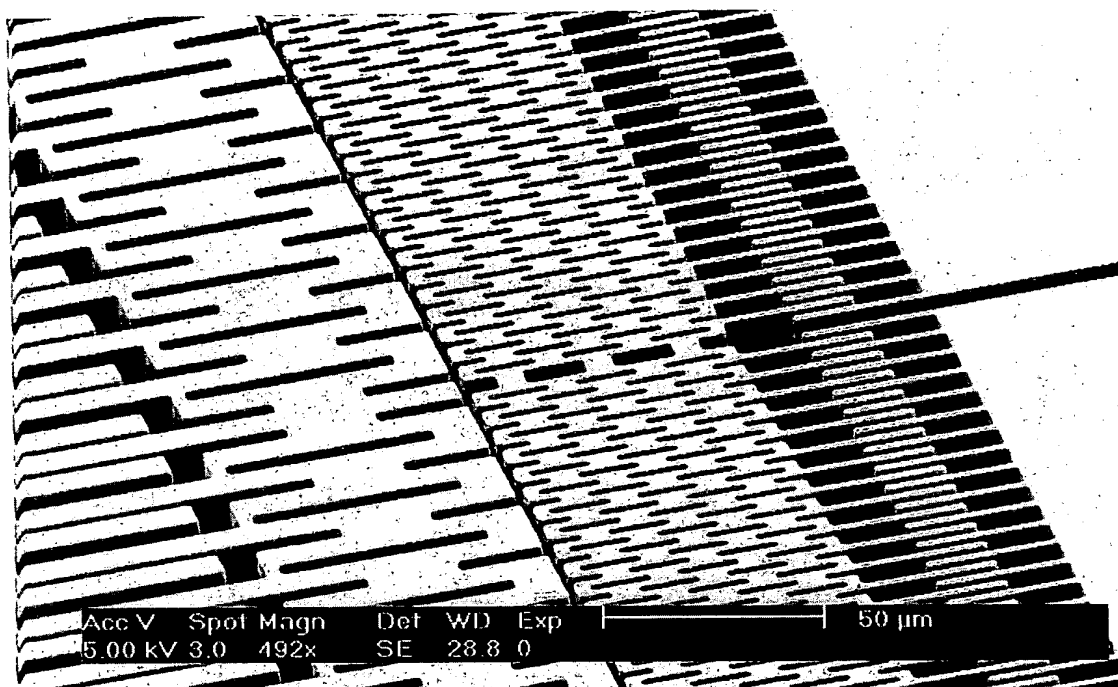




FIG. 13

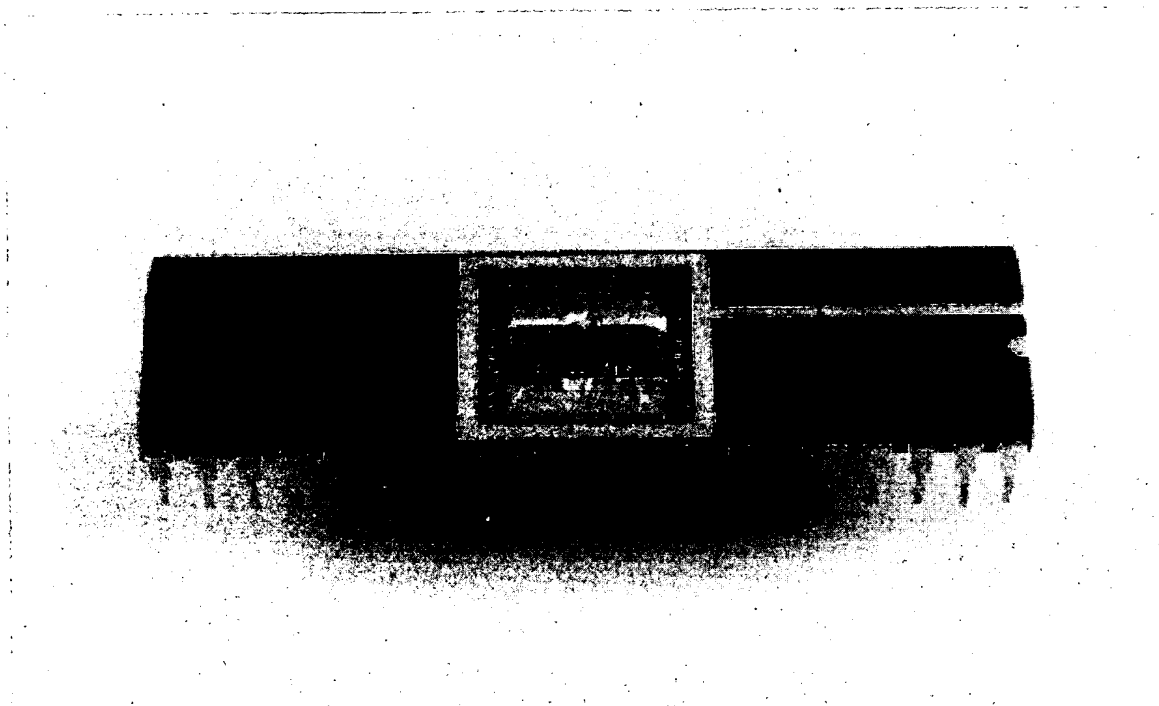
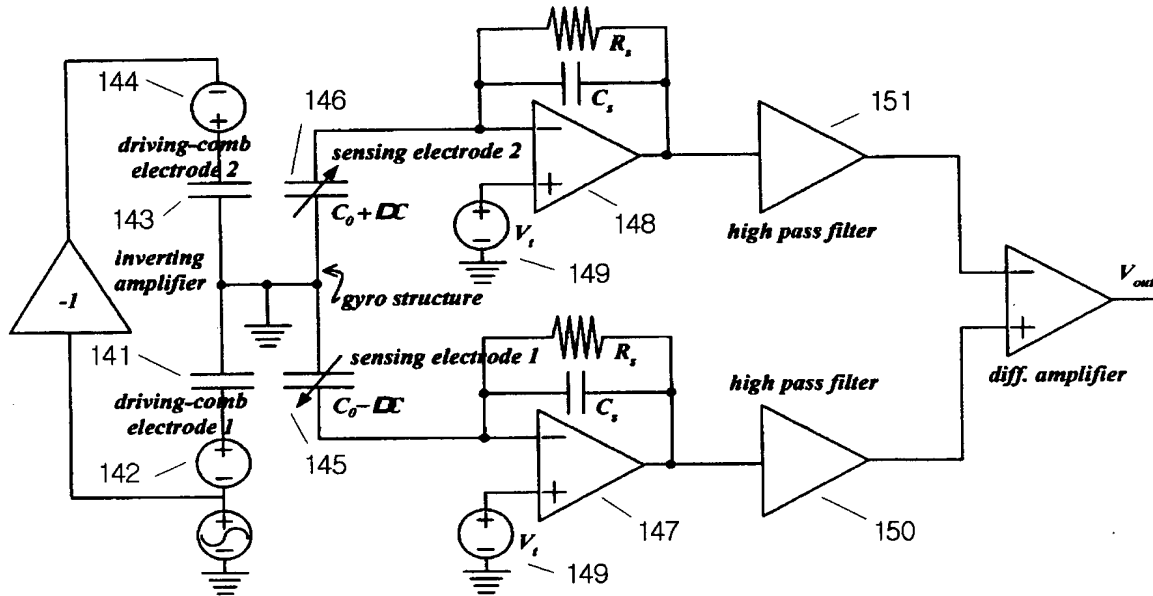




FIG. 14



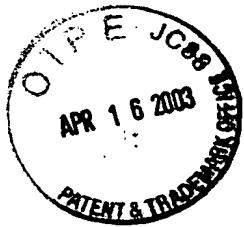
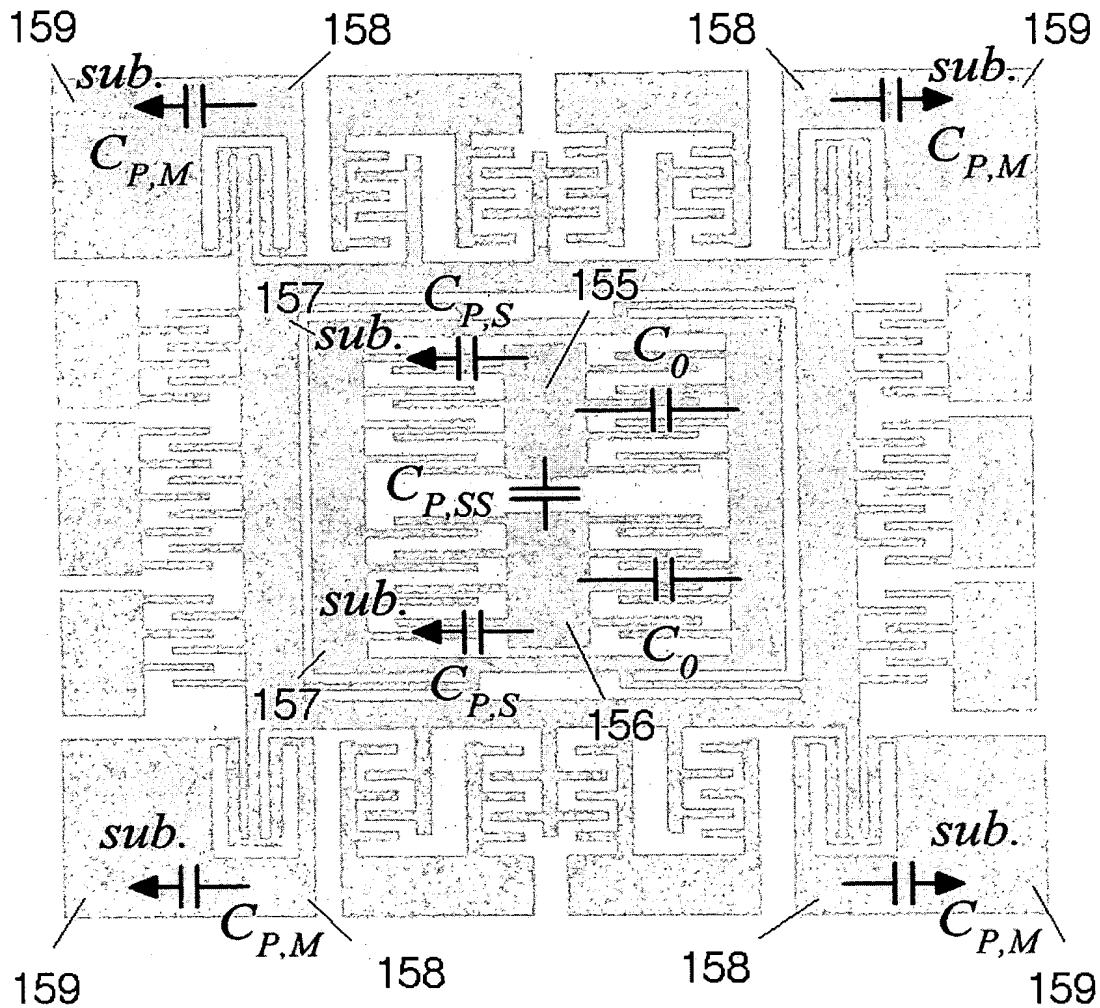


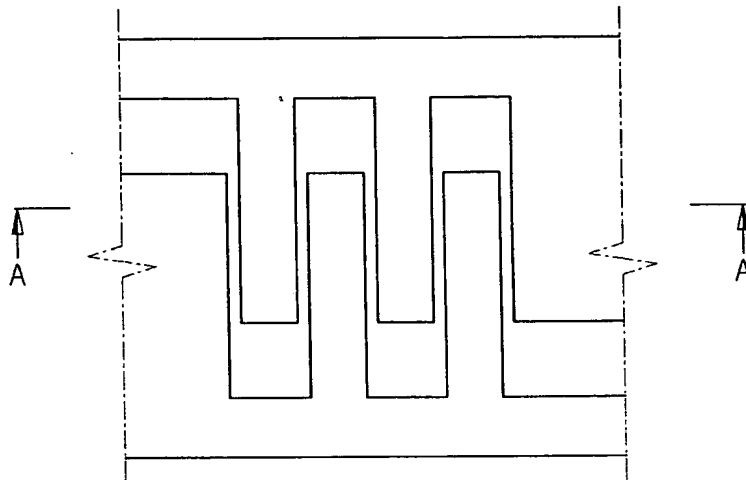
FIG. 15A







[Fig. 20]



[Fig. 21]

